



Material Content Data Sheet



Sales Product Name		ICE2A180Z		Issued		29. August 2013		
MA#		MA001086268						
Package		PG-DIP-7-4		Weight*		653.08 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.565	0.85	0.85	8521	8521
leadframe	inorganic material	phosphorus	7723-14-0	0.049	0.01		74	
	non noble metal	zinc	7440-66-6	0.194	0.03		297	
	non noble metal	iron	7439-89-6	3.884	0.59		5948	
wire	non noble metal	copper	7440-50-8	157.726	24.15	24.78	241512	247831
	noble metal	gold	7440-57-5	0.178	0.03	0.03	272	272
	encapsulation	organic material	carbon black	1333-86-4	1.424	0.22		2181
encapsulation	plastics	epoxy resin	-	46.049	7.05		70511	
	inorganic material	silicondioxide	60676-86-0	427.261	65.43	72.70	654229	726921
leadfinish	non noble metal	tin	7440-31-5	6.460	0.99	0.99	9891	9891
plating	noble metal	silver	7440-22-4	1.911	0.29	0.29	2926	2926
glue	plastics	epoxy resin	-	0.356	0.05		546	
	noble metal	silver	7440-22-4	2.019	0.31	0.36	3092	3638
*deviation	< 10%					Sum in total:	100,00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com